

E by DEK - ASM Inline Solder Paste Printer

I. Features

1. E-Quality

DEK's experienced printing specialists have developed an innovative platform for E by DEK with high-quality components, sophisticated construction, and modular design that guarantees a stable and reliable printing process even for the latest fine-pitch applications.



2. E-Performance

The E by DEK delivers E-Performance with:

8 seconds core cycle time

Fast setup changeovers

High repeatability

With the shortest cycle times and the fastest product changeovers paired with maximum repeat accuracy, the E by DEK sets new standards in the mid-speed segment.

3. E-Facts

Clearly structured, and each number provides a strong argument: The most important facts and figures on the E by DEK.

* Alignment qualifications include board loading/unloading, board clamping, camera/table movement. Capability value is calculated with 3rd-party QC-Calc software.

Machine capability comprises board loading/unloading, board clamping, camera/rising table movement and print process. The capability value is calculated with 3rd-party QC-Calc software.

4. E By DEK

Flexibility at its best!

Each SMT factory has its own special challenges. That is why we have developed Options for the E by DEK that allow custom tuning with perfectly coordinated modules for printing results that will make your customers happy and raise your SMT production to a new level.

5. E by DEK Options for all your applications

Throughput
Quality
Flexibility
Long and heavy circuit boards

II. Technical Parameters

Model	DEK E by
Alignment	> 2.0 Cmk @ $\pm 12.5 \mu\text{m}$ (± 6 sigma)
System alignment capability	> 2.0 Cmk @ $\pm 25 \mu\text{m}$ (± 6 sigma)
Optimum core cycle time	8 seconds
Substrate size	50 mm (X) x 40.5 mm (Y) to 620 mm (X) x 508.5 mm (Y)
Operating System	Windows 7 Embedded
Squeegee pressure mechanism	Software-controlled, motorized with closed loop feedback
Stencil positioning	Semi-auto stencil load with drip tray
Understencil cleaning	Interchangeable understencil cleaner (IUSC), fully programmable with wet/dry/vacuum wipe
Adjustable-width stencil mount (AWSM)	Frame variants - fully adjustable to accommodate frame sizes in the range of 381 mm to 736 mm
Substrate thickness	0.2 mm to 6 mm
Substrate weight (max)	6 kg
Substrate warpage	Up to 7 mm including substrate thickness
Substrate fixture	Over the top clamp Edge clamp Foil-less clamp Vacuum
Temperature & humidity sensor	Monitoring of the process environment